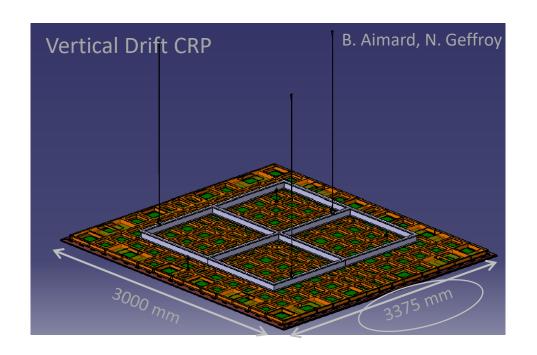
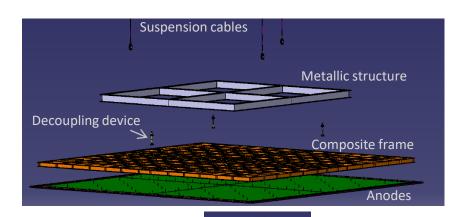
CRP consortium meeting: 17/03/2021

- Status of activities for preparing CRP of cold box tests
- Far Detector WBS
- Status of anode design and options for connecting the PCBs

Vertical Drift CRP for test in cold box



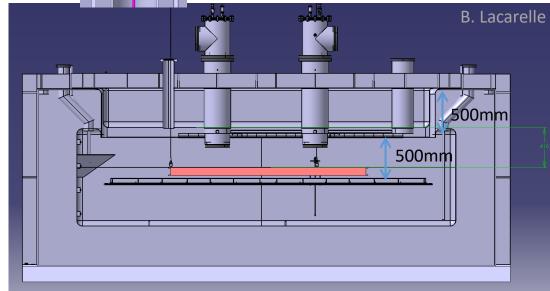


Keep original suspension system with 40mm bellows

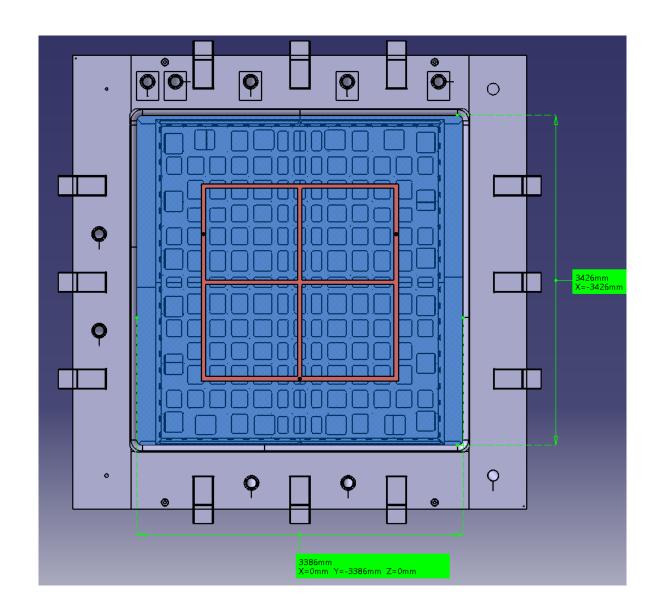
The opening of the cold box is being increased to allow vertical insertion of the CRP with no need to have an inclination of the structures

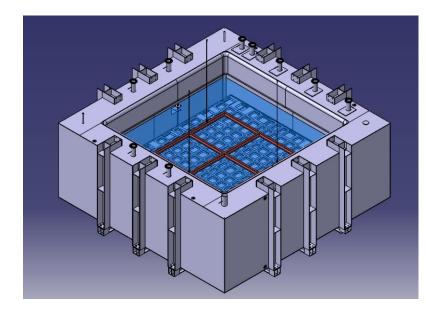
Some optimisation going on to complete with the udpated cold box model





Vertical Drift CRP for test in cold box





Goal:

centre the 3373 x 2998 mm² CRP wrt CB opening

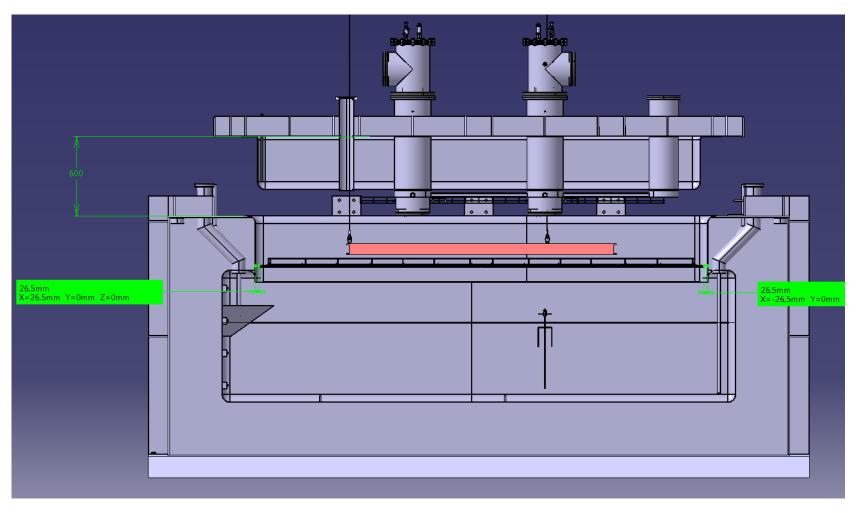
will lead to:

- 26,5mm clearance / length (3373mm)
- 194mm clearance / width (2998mm)

Vertical Drift CRP for test in cold box

3373 x 2998 mm² CRP centered wrt CB opening

During insertion

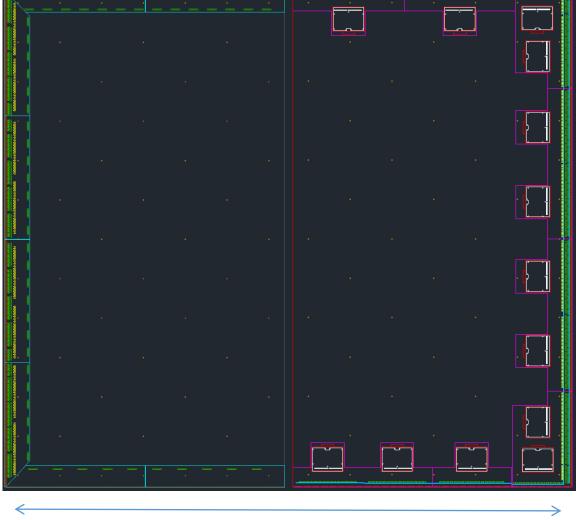


26,5mm clearances / length (3373mm)

Design for the support structure

Final hole pattern «

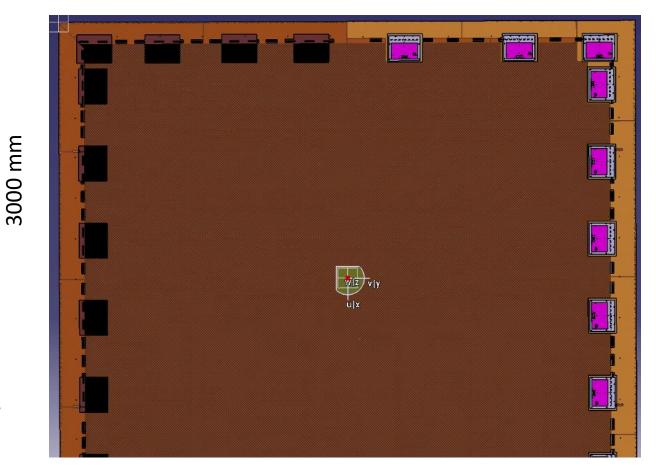
« support » layer = 58 holes



Hybrid structure:

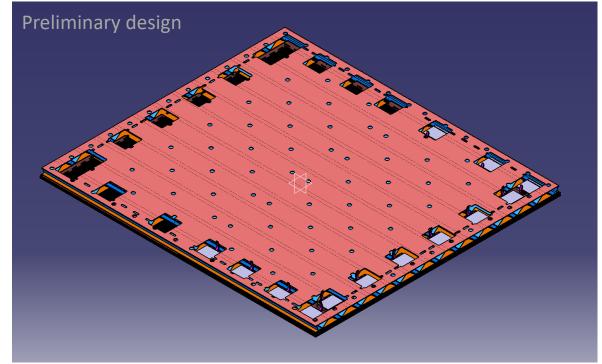
the same structure useable for both electronics (individually or mixed)

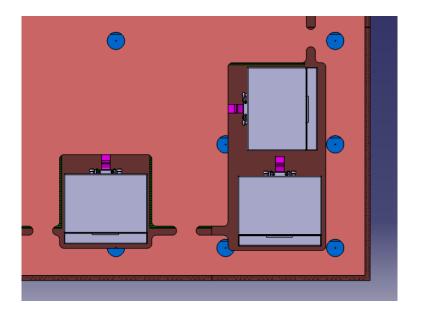
=> Openings along the sides of the frame to allow CE module connection and the connectors for top electronics



Mechanical structure: design at LAPP ongoing

Based on the 3D CAD model of the anode, adapter boards and CE box <u>distributed</u> last week (March 9th)

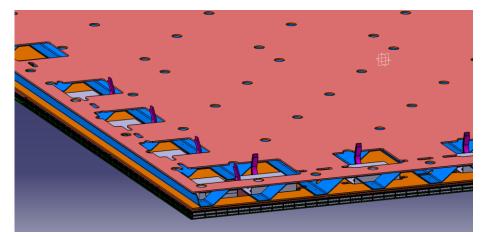






next steps:

- Deformation modelisation with all component weight and positions
- Optimise additional opening depending on the results
- Confirm the CTE of the foreseen material compatible with anode material



CRP support frame design steps:

- Anode support hole pattern defined and frozen 3/03/21
- Support frame + anode material CTE measurements at Cryolab ongoing: expect results by 15/03/21
- Integration of 3D model of anode + adapter Boards + CE box (on going)
- Mechanical simulation to be done with the proper weight and component distribution

The 3D models for the CE FEMB and Boxes: use the ProtoDUNE-SP version for the time being.

CRU assembly (before the CRP assembly)

Discussion ongoing to understand how to manipulate the large PCB anodes and the needs for tooling. => depending on this discussion toolings may have to be designed

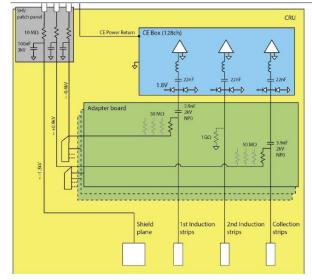
Points under study:

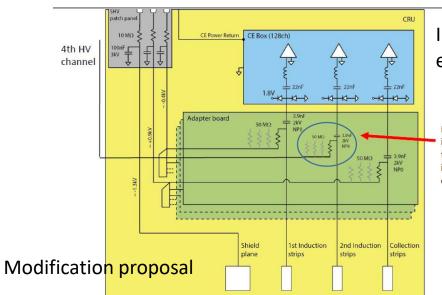
- Connector type, positioning and soldering (next item on the agenda)
- Anode manipulation during the CRU assembly

Adapter boards for the top electronics

After discussion last week it appears that some modifications are needed to treat identically induction 2 as for the 2 other strip directions.

Original schema





In discussion with the top electronics

Make connections for induction 2 similar as the other strips including the decoupling capacitors and 50 Mohm

Work started in order to go into the details and timing

- Anodes and CRUs (BNL, CERN)
- Top electronics interface (KEK, Lyon, BNL, CERN)
- Bottom electronics (BNL, FNAL, CERN)
- CRP structure components (LAPP)
- CRP assembly (from assembled CRUs to CRP) (LAPP, ...)
- CRP transport box design and production (LAPP)
- CRP transport box design and production (LAPP)
- CRP instrumentation (LPSC, CERN,)

<u>Terminology</u>

- ☐ PCB anode <u>subpanel</u>: <u>perforated</u> PCB unit <u>produced</u> by the <u>company</u> 1.7m x0.5m
- ☐ CRU layer: PCB anode layer made of 6 subpanels glued together = 1.7m x 3m
- ☐ The anode PCB with shield and induction#1 strips is called « shield layer »
- ☐ The anode PCB with induction#2 and collection strips is called « collection layer »
- ☐ a CRU is made of 1 shield layer + 1 collection layer + adapter boards

Task list for first CRP production for cold box test:

Anode and CRUs (BNL, CERN)

Anodes (perforated)

- design and gerber file week of March 15
- PCB procurement week of March 22
- PCB anode production 6 weeks from the time of placing the order. mid April beginning of June
- anode reception beginning-mid of June

Connecting devices (to link the 2 PCB layers called 'shield' and 'collection' and connect the adapter boards)

- procurement - - April-May

PCB Manipulation tooling (depends on connection and assembly technics procedure)

- design April?
- part procurement April-May?
- reception and assembly June?

Anode and CRUs (BNL, CERN) PA

PART 2

CRU#1 shield layer

- gluing from 6 subpanels 1 day/gluing and drying 1 week total
- Silver connection painting 1 day for painting and drying. 1 week total (try to <u>parellelize</u> with gluing) 1 week additional in conservative estimation if we cannot parallelize with gluing
- Connector installation and soldering (depends on technical choices) if pogo pins --> may be automated?. If manual soldering -> meeting with CERN electronics assembly workshop supervisor to know more
- Electrical test 1-2 days

-- Dates: start mid June, finalize end of June

(for silver paint: assume polymerization at room temperature)

Manual soldering of connectors: for the 4 CRUs is 1 week

CRU#2 shield layer

- gluing from 3 subpanels same as above
- Silver connection painting same as above
- Connector installation and soldering (depends on technical choices) same as above
- Electrical test same as above
- -- Dates: start beginning of July, finalize mid of July

Anode and CRUs (BNL, CERN)

CRU#1 collection layer

- gluing from 3 subpanels same as above
- Silver connection painting (assume polymerization at room temperature) same as above
- Connector installation and soldering (depends on technical choices) same as above
- Electrical test more channels here. 1 week of testing (induction-2 + collection)

PART 3

-- Dates: assume we'll get faster with gluing and painting. Then the gained time can be used for testing. Start mid July, finalize end of July

CRU#2 collection layer

- gluing from 3 subpanels same as above
- Silver connection painting (assume polymerization at room temperature) same as above
- Connector installation and soldering (depends on technical choices) same as above
- Electrical test 1 week
- -- Dates: assume we'll get faster with gluing and painting. Then the gained time can be used for testing. Start begining of August, finalize mid of August

Anode and CRUs (BNL, CERN)

CRU#1 (made of 2 PCB anode layers + adapter boards)

- mechanical assembly and connection of both layers This is a handling process where we need to bring the two units together to attach them. Manipulating them precisely 1-2 days. (If we need to install spacers or something like that for the CRP mechanical structure it may take 1-2 more days.)
- installation of adapter boards 1-2 days
- control test 1-2 days (warm noise/functionality test with electronics)

PART 4

?? cold test?? – should we plan some test?

-- Dates: 1 week from mid August

CRU#2 (made of 2 PCB anode layers + adapter boards)

- mechanical assembly and connection of both layers same as CRU#1
- installation of adapter boards same as CRU#1
- control test same as CRU#1

??cold-test?? - should we plan some test?

-- Dates: 1 week at the end of August

Task list for first CRP production for coldbox test:

_____ Top Electronics interface (KEK, BNL, CERN) _____ - connector procurement adapter boards -design -part procurement (PCB + resistors + capacitors) -fabrication (including connector soldering) _____ Bottom Electronics (FNAL, BNL, CERN) _____ adapter boards -design -part procurement (PCB + resistors + capacitors) -fabrication -CE FEMB -Power and data cables - CE boxes design procurement

CRP structure components (LAPP) _____ CRP composite support structure - material characterisation (CTE) by mid March - concept drawing (composite vs PCB assembly) by mid March - design (beginning of April) - procurement (end of April) - production (6 weeks=> mid June) CRP metallic frame - design (April) - procurement (mid April) - production (5 weeks => end of May) CRP decoupling system - design (mid April) - prototype and test (end of April) - procurement (mid May) - production (?) CRP suspension feedthroughs (use same below and flange as previous cold box tests) - manual winch system design - procurement - production _____ CRP transport box (LAPP, ...) (could be based on additional elements to the existing metallic frame) _____ CRP transport box - design - part procurement - assembly - (Manutention test?)

CRP assembly (from assembled CRUs to CRP) (LAPP, ...) _____

CRP mounting procedure definition

CRP mounting tooling

- design
- part procurement
- reception and assembly

All this assembly planning has to be defined; olt depends strongly on some technical choices of anodes and CRU assembly

Metallic frame attachment

CRU attachment to support frame

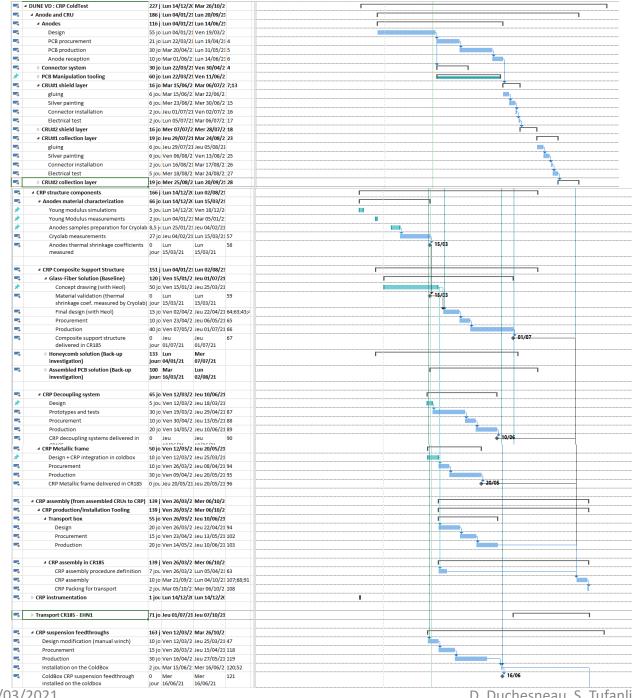
CE module cable routing

Instrumentation (Pt/level meter..) installation and cabling

CRP instrumentation (LPSC, CERN, ...) _____

Sensor

- part procurement (sensor + Read Out electronics + cables)



Task list for first CRP production for coldbox test:

First draft version of the detailed project schedule

Procedures are being refined

A preliminary version available by next week

In the mean time the WBS for the FD2 module is being developed: CRP and CRU are 2 elements

| 4 A | В | C | D E | F | G | H I | J | К | L . | | М | | | | |
|---------------------------------------------|------------------------------------|---------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------|----------------------|---------------------|------------------------------|--------------------|----------------------------------------------|-------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|--------|-----|
| WBS Element # | WBS Element Name | Inst | Activity Name | Simple Resource | Resources (Optional) | Labo Non r Labor | Curren F | Predeces sor ID | Notes | | WBS Dictiona | ry | | | |
| 131.02.04 | Far Detector 2 (FD-2) | | | | | Labor | | | | | | | | | |
| 131.02.04.01 | FD-2 Project Management | | | | | | | | | Project Manag costs for the pr | ement costs for Far Detector-2 (oject staff, incidental costs for re | FD-2) including M&S and travel views and project coordination. | | | |
| 131.02.04.02 | FD-2 Charge Readout Units (CRU) | | | | | | | | | DOE, CERN ar the PCB and a conjunction wit DOE: Procurer sites. The CRF CERN, internat | d international partners: Design, I lapter boards. The prototyping in I US, CEFNI and international pa hent, assembly and shipment of b assembly site is covered in a sel onal partners: Procurement, ass | orototyping, prototype testing of d design phases will be done in theres ottom CRU to CRP assembly arate WBS. embly and shipment of the Top | | | |
| 131.02.04.02.01 | CRU Management | | | | | | | | | CRU to CRP a | ssembly sites will be done in Euro | pe. | | | |
| 31.02.04.02.01 | Anode PCBs | | | | | | | | | _ | | | | | |
| 131.02.04.02.02.01 | Anode PCB design | DOE | | | | | | | | spec and proci | or connectors comes from here | then ship to CRP aslu factoru | | | |
| | - | | 1 Anode PCB design | Scientist | | 100 | | | | | | | | | |
| | | | 2 Design validation | Scientist | | 40 | 1 | 1 | | | | | | | |
| | | | 3 gerber file preperation | Technician | | 20 | 2 | 2 | | | | | | | |
| | | | | | | | | | | | | | | | |
| 3 131.02.04.02.02.02 | Anode PCB fabrication | DOE | | | | | 53 | | | | 3 Assemble 2 layers of PCB | | 40 | P | 1,2 |
| 101.02.04.02.02.02 | minose i Cop raprication | 306 | 1 collecting quotations and decide | Scientist | | 40 | 54 | 4 00 0F | | | 4 Connecting interface board Anode assembly | s to the Scientist | 40 | | 3 |
| | | | company 2 placing the order | Scientist | + | 10 | 55 131.02.04 | 04.02.05.02 | Ship to CRP top assembly sites | CERN++ | Drop systian and hull discount | inning container99 | + | + | |
| 6 | | - | 2 placing the order 3 fabrication of PCBs and drilling | M&S | + | 4160 2000000 | 57 | | + | - 1 2 | Preparation and building sh Preparation of CRU for shi | pping container?? | 20 | + | -+ |
| 7 131.02.04.02.02.03 | Anode PCB gluing | CERN++ | 5 ASSIGNATION CDS and drilling | 1 | + | ,100 2000000 | 58 | | 1 | | 2 Shippment | M&S | 120 | | -+ |
| 8 | | | 1 gluing PCBs | Technician | | 640 60000 | 59 131.02.04 | 04.02.06 | CRU bottom | | | | | | |
| 9 | | | 1 gluing PCBs | Technician | | 640 60000 | 60 131.02.0 | | CRU Bottom assembly | DOE | | | | | |
| 20 131.02.04.02.03 | Interface cards top | | | | | | 61 | | | | 1 preparing assembly area | Technician | 200 | | |
| 21 131.02.04.02.03.01 | Interface cards top design | DOE | | | | | 62 | | | | preparing necessary handling | g devices Mechanical Engineer | 200 | \top | |
| 22 | | | 1 design | Scientist | | 40 | 62 | | | | and tools for assembly | - 4 | | | |
| 3 | | | 2 validation | Scientist | | 20 | — ₆₃ | | | | and tools for assembly | Technician Technician | 200 | | |
| 5 131.02.04.02.03.02 | lekeriere endeken fehrierkier | | 3 gerber file preperation | Technician | + | 10 | 64 | | | | 3 Assemble 2 layers of PCB | Scientist | 40 | h | 1.2 |
| 5 131.02.04.02.03.02 | Interface cards top fabrication | DOE | 1 interface card PCB production | M&S | | XX | 65 | | | | 3 Assemble 2 layers of PCB | Technician | 40 | , A | 1,2 |
| 131.02.04.02.03.03 | Interface cards top assembly | CERN++ | I Interrace card PCB production | Mas | + | ^^ | 66 | | | | 3 Assemble 2 layers of PCB | Scientist Uncosted - Generic Univ | 40 | 1 | 1,2 |
| 101.02.04.02.03.03 | interrace cards top assembly | | 1 component procurement | M&S | + | XX | _ | | | | 4 Connecting interface board | s to the Scientist | 40 | | 2 |
| 29 | | | 2 component soldering | Technician | | XX | 67 | | | | * Anode assembly | Sciences | 10 | | |
| 30 | | | 2 component soldering | Technician | | XX | - 68 131.02.04 | 04.02.06.02 | Ship to CRP bottom assembly sites | DOE | | | | | |
| 31 | | | 3 quality checks | Scientist Uncosted - Generic Univ | | 40 | 69 | | | | Preparation of CRU for shi Shippment | oping Technician | 20 | | |
| 32 | | | 3 quality checks 3 quality checks | Scientist Uncosted - Generic Univ | | 40 | - 10 | | | | 2 Shippinent | IVIIXO | | | - |
| 33 131.02.04.02.04 | Interface cards bottom | | | | | | 131.02.0 | 04.02.07 | CRU teststands, CRU-CRP installation eqp. QC | | | | | | |
| 34 131.02.04.02.04.01 | Interface cards bottom design | DOE | | | | | 71 | | | | | | | | |
| 35 | | | 1 design | Scientist | | 20 | 72 | | | | Preparation of testing facili | ty Scientist | 1000 | | |
| 36 | | | 2 validation | Scientist Technician | + | 10 | 73 | | | | Preparation of testing facili | ty Technician | 1000 | | |
| 38 131.02.04.02.04.02 | Interface cards bottom fabrication | DOE | 3 gerber file preperation | Technician | + | 10 | 74 | | | | Procuring necessary hardw QC tests on the CRU units | are for tes Scientist | 400 2000 | | 40 |
| 39 | interrace cards porton raprication | DOE | 1 interface card PCB production | M&S | + | XX | 76 | | | | 3 QC tests on the CRU units | Scientist Scientist Uncosted - Generic Univ | 2000 | | 12 |
| 40 131.02.04.02.04.03 | Interface cards bottom assembly | DOE | 1 Interrest out at the production | 1-100 | | | - 10 | | | | 5 QC tests on the Crib dilits | Sciencist oncosted - denenic only | 2000 | | ,2 |
| 41 | | | 1 component procurement | M&S | | XX | | | | | | | | | |
| 42 | | | 2 component soldering | Technician | | XX | | | | | | | | | |
| 43 | | | 2 component soldering | Technician | | XX | | | | | | | | | |
| 44 | | | 3 quality checks | Scientist Uncosted - Generic Univ | | 40 | 131.02.04 | 04.03 | FD-2 Charge Readout Plane (CRP) | | | | | | |
| 45 101.00.01.00.0E | OPUL | | 3 quality checks | Scientist Uncosted - Generic Univ | | 40 | _ | | | | | | | | |
| 46 131.02.04.02.05 47 131.02.04.02.05.01 | CRU top CRU Top assembly | CERN++ | | | | | _ | | | | | | | | |
| 48 | Onto rop assembly | CERINA | 1 proporing accombly area | Technician | + | 200 | _ | | | | | | | | |
| | | | and the second s | | | 200 | 77 | | | | | | | | |
| 49 | | | 2 and tools for assembly | rviecnanical Engineer | | 200 | 78 131.02.04 | | CRP Management | | | | | | |
| | | | preparing necessary handling devices | Tooknisisn | | 200 | 79 131.02.04 80 131.02.04 | 14.03.02 | Anode support structure frame top | IN2P3 | | | | | |
| 50 | | | and cools for assembly | | 1 | | 80 131.02.04 | P4.03.02.01 | Design | INZP3 | 1 Design of the second | Garage Marchanian Francis | 100 | + | |
| 1 | | | 3 Assemble 2 layers of PCB | Scientist | | 40 | 81 | | | | Design of the composite | frame Mechanical Engineer | 100 | + + | + |
| 52 | | | 3 Assemble 2 layers of PCB | Technician | 1 | 40 | 92 | | | | Design of the composite Material characteristation | | 100 | | - |
| | | | | | | | 84 131.02.04 | 04.03.02.02 | Part procurement | IN2P3 | acenaronaraccelistatio | . Preorianical Engineer | | + + | |
| | | | | | | | 85 | | | 1 | 1 Do the tendering and de | cide Mechanical Engineer | 10 | | |
| | | | | | | | 86 | | | | 2 Place the order | Mechanical Engineer | 10 | 1 1 | 1 |
| | | | | | | | 87 131.02.04 | 14.03.02.03 | Assembly | IN2P3 | | | | | |
| | | | | | | | | | | | 1 Fabrication of the top CF | P M&S | 800000 | Eur | |
| | | | | _ | | | 88 | 04.03.02.04 | Chin to CDD ton accomiting the | IN2P3 | structure frame | 1 | 300000 | 1 | |
| Dod | icated meetin | a nov | t Thursday | to rovious | , tha | | 89 131.02.04 | r+.03.02.04 | Ship to CRP top assembly sites | | 1 propore the trans | n Technician | 10 | + | + |
| DEU | ווכמנכט וווככנווו | K IIC | KL THUISUAV | to review | uie | | 91 | | 1 | | prepare the transportation Shipment | M&S | 10 888888 | 1 1, | 1 |
| | | 9 | | | | | 92 131.02.04 | 04.03.03 | Anode support structure frame bottom | | - propriets | 1100 | ANNAN | | |
| 100 | | | | <u> </u> | | | | 4.03.03.01 | Design Design | IN2P3 | | | | | |
| dec. | cription of acti | MITIE | s in the W/R | | | | 94 | | | | 1 Design of the composite | frame Mechanical Engineer | 100 | | |
| ucs | | IVILIC. | S III CIIC VVD | - | | | 95 | | | | Design of the composite | frame Scientist | 100 | | |
| | | | | | | | 96 | | | | Material characteristation | n Mechanical Engineer | 10 | 1 | 1 |
| | | | | | | | 97 131.02.04 | 04.03.03.02 | Part procurement | IN2P3 | | | | | |